

View Online at <https://aerobasegroup.com/nsn/5910-01-418-3456>

**Body Style:**

Chip type

**Reliability Indicator:**

Established

**Reliability Failure Rate Level In Percent:**

0.010

**Terminal Length:**

0.5 millimeters

**Body Length:**

3.2 millimeters

**Body Width:**

2.5 millimeters

**Body Height:**

0.5 millimeters

**Schematic Diagram Designator:**

No common or grounded electrode (s)

**Insulation Resistance At Maximum Operating Temp:**

1000.0 megohms

**Capacitance Value Per Section:**

2200.000 picofarads single section

**Nonderated Operating Temp:**

Between -55.0 degrees celsius and 125.0 degrees celsius

**Temperature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:**

0.0 single section

**Nonderated Continuous Voltage Rating And Type Per Section:**

100.0 dc single section

**Tolerance Of Temperature Coefficient Per Section In Ppm Per Deg Celsius:**

-30.0/+30.0 single section

**Tolerance Range Per Section:**

-1.00/+1.00 percent single section

**Case Material:**

Ceramic

**Insulation Resistance At Reference Temp:**

100000.0 megohms

**Dissipation Factor At Reference Temperature In Percent:**

0.150

**Terminal Surface Treatment:**

Solder

**Test Data Document:**

Mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

**Terminal Type And Quantity:**

2 bonding pad

**Specification Data:**

Mil-c-55681/9 government specification

**Shelf Life:**

N/a

**Unit Of Measure:**

--

**Demilitarization:**

Yes - demil/mli

**Fig:**

A010b0

**Mil-std (military Standard):**

Mil-c-55681 spec.